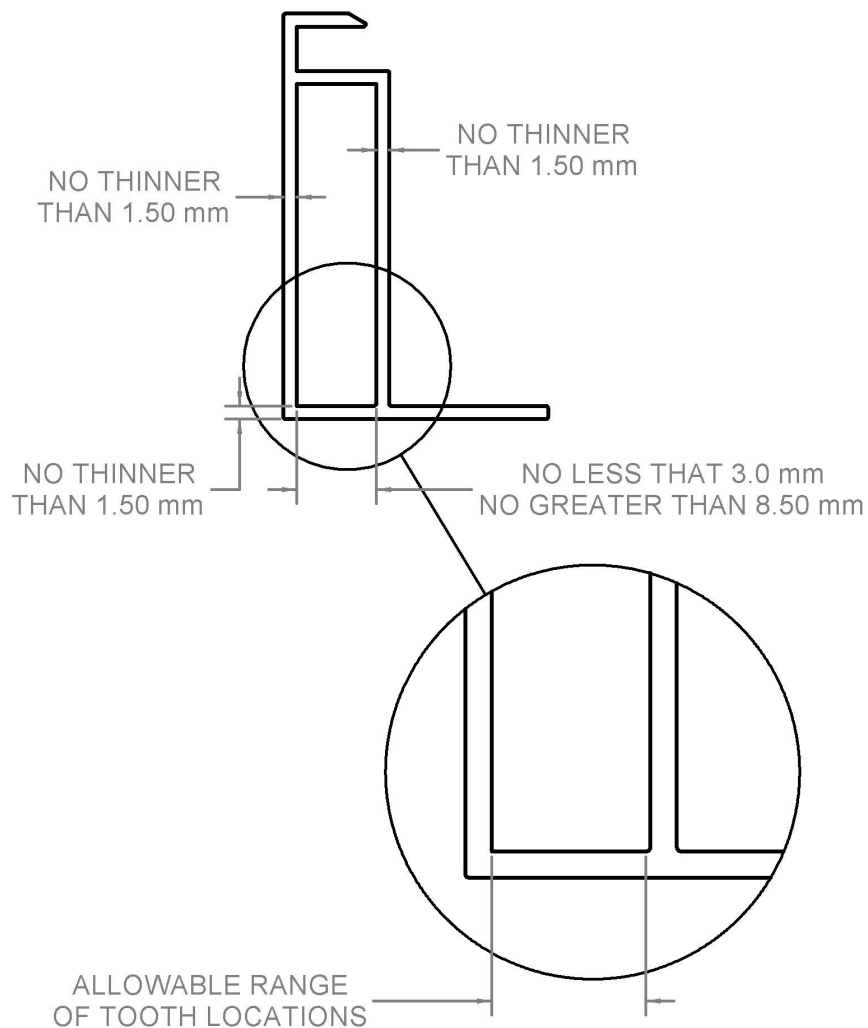


July 9, 2010

Re: WEEB compatibility with thin PV module frames

To: PV module installers who use the WEEB bonding and grounding system

The findings of recent testing have confirmed that certain module frames are not substantial enough to effectively create a ground bond using WEEB products, when WEEBs are installed at the inter-module clamp. The general requirements for minimum module frame thickness of “boxed” type module frames are illustrated below.





WILEY ELECTRONICS, LLC  
PO BOX 361  
SAUGERTIES NY 12477  
845.247.4708 office  
845.839.2792 fax  
[www.we-llc.com](http://www.we-llc.com)

The following is a list of modules manufactured by Sharp Electronics Corporation that are not compatible with the WEEB bonding washer.

- NA-V115H5 – Thin Film (IEC)
- NA-V121H5 – Thin Film (IEC)
- NA-V128H5 – Thin Film (IEC)
- NA-V142H5 – Thin Film (IEC)
- NA-V135H5 – Thin Film (IEC)
- NA-V115H1 – Thin Film (UL)
- NA-V121H1 – Thin Film (UL)
- NA-V128H1 – Thin Film (UL)
- NA-V135H1 – Thin Film (UL)

Module frames that fall outside of these specifications must be tested and approved for use by Wiley Electronics.

Paul Kovalov  
Project Engineer  
Wiley Electronics, LLC.  
[paul@we-llc.com](mailto:paul@we-llc.com)  
(845) 247-4708